




Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32L452RCI6	P221*462XXXY	A	9996	2018-09-03
	Amount	UoM	Unit type	ST ECOPACK Grade
	26.800	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
SOLDERBALL (Sn96.5Ag3.5)	NAC	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
BGA	5,5,0,6	64	No lead	
Comment	Package : A019 UFBGA 5X5X0.6 64L P 0.5 MM 8526322			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	P221*462XXX				6000000.0	0.0				
note : Substance present with less 0.001mg will not be declared in this document																
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	2.612	mg	supplier	die	Silicon (Si)	7440-21-3		2.188	mg	837672	81642				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.020	mg	7657	746				
				supplier	metallization	Copper (Cu)	7440-50-8		0.180	mg	68913	6716				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.058	mg	22205	2164				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	766	75				
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	766	75				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.046	mg	17611	1716				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.116	mg	44410	4328				
				supplier	CORE	Glass Cloth	65997-17-3		0.512	mg	57700	19120				
				supplier	CORE	Epoxy resin	61788-97-4		0.092	mg	10400	3446				
SUBSTRATE (DS7409HGB)	M-011 Other inorganic materials	8.881	mg	supplier	CORE	Flame resistant epoxy resin	223769-10-6		0.082	mg	9200	3049				
				supplier	CORE	Heat resistant resin	25722-66-1		0.082	mg	9200	3049				
				supplier	CORE	Silica filler	7631-86-9		0.194	mg	21900	7257				
				supplier	CORE	Metal Hydroxide	Proprietary		0.154	mg	17300	5733				
				supplier	CORE	Copper foil	7440-50-8		0.933	mg	105000	34795				
				supplier	SOLDERMASK (AUS308)	Talc containing no asbestiform fibers	14807-96-6		0.073	mg	8200	2717				
				supplier	SOLDERMASK (AUS308)	Barium sulfate	7727-43-7		1.218	mg	137200	45465				
				supplier	SOLDERMASK (AUS308)	Dipropylene glycol monomethyl ether	34590-94-8		0.491	mg	55300	18325				
				supplier	SOLDERMASK (AUS308)	Napthalene	91-20-3		0.187	mg	21000	6959				
				supplier	SOLDERMASK (AUS308)	Morpholine derivative	Proprietary		0.204	mg	23000	7622				
				supplier	CU PLATING	Copper (Cu)	7440-50-8		3.160	mg	355800	117904				
				supplier	NI PLATING	Nickel (Ni)	7440-02-0		1.309	mg	147400	48845				
				supplier	AU PLATING	Gold (Au)	7440-57-5		0.190	mg	21400	7091				
				DIE ATTACH (ATB-130U)	M-011 Other inorganic materials	0.322	mg	supplier	GLUE	Butadiene,acrylonitrile polymer,carboxy-termi	68610-41-3		0.226	mg	700000	8418
								supplier	GLUE	Phenol-formaldehyde polymer	9003-35-4		0.032	mg	100000	1203
supplier	GLUE	Phenol polymer with formaldehyde,glycidyl et	28064-14-4						0.030	mg	92000	1106				
supplier	GLUE	Dapsone	80-08-0						0.031	mg	97000	1166				
supplier	GLUE	Reaction product bisphenol-A-(epichlorhydrin	25068-38-6						0.003	mg	10000	120				
supplier	GLUE	4,4, Isopropylidenediphenol	80-05-7						0.000	mg	1000	12				
BONDING WIRE (MKE 4N)	M-011 Other inorganic materials	0.289	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		0.289	mg	1000000	10791				
SOLDERBALL (Sn96.5Ag3.5)	M-011 Other inorganic materials	1.987	mg	supplier	SOLDERBALL	Tin (Sn)	7440-31-5		1.918	mg	965000	71557				
				supplier	SOLDERBALL	Silver (Ag)	7440-22-4		0.070	mg	35000	2595				
ENCAPSULATION (GE-100LFC5)	M-011 Other inorganic materials	12.708	mg	supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		11.395	mg	900000	-574804				
				supplier	MOLDING COMPOUND	Epoxy resin	Proprietary		0.591	mg	45000	22048				
				supplier	MOLDING COMPOUND	Phenol resin	Proprietary		0.525	mg	40000	19599				
				supplier	MOLDING COMPOUND	Metal Hydroxide	Proprietary		0.131	mg	10000	4900				
				supplier	MOLDING COMPOUND	Carbon black	1333-86-4		0.066	mg	5000	2450				